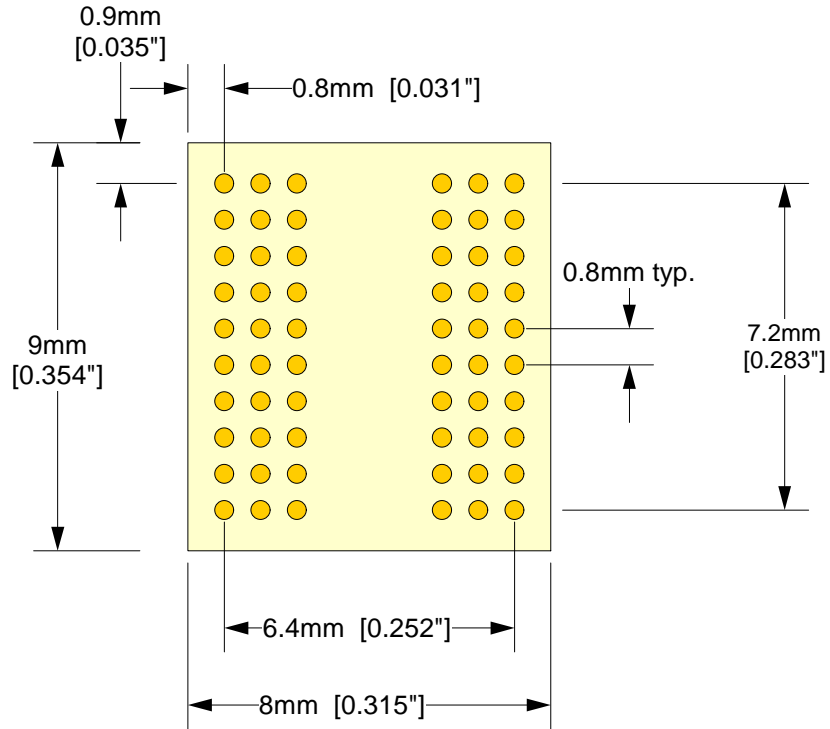
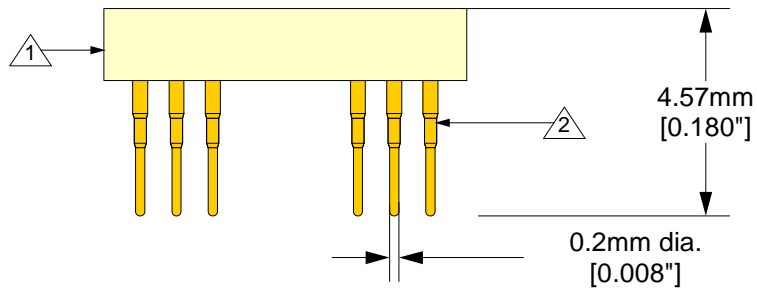


Top View



Side View




- ① Substrate: 1.59mm \pm 0.18mm [0.0625" \pm 0.007"] FR4/G10 or equivalent high temp material; Non-clad
- ② Pins: material- Brass Alloy 360 1/2 hard; finish- 0.25 μ m [10 μ] Au over 1.27 μ m [50 μ] Ni (min.).

Description: Giga-snaP BGA SMT Foot

60 position terminal pins (0.8mm centers, 8x10 array) to SMT solder balls (BGA type). Pin assignment 1:1.

Tolerances: diameters \pm 0.03mm [\pm 0.001"], PCB perimeters \pm 0.13mm [\pm 0.005"], PCB thicknesses \pm 0.18mm [\pm 0.007"], pitches (from true position) \pm 0.08mm [\pm 0.003"], all other tolerances \pm 0.13mm [\pm 0.005"] unless stated otherwise. Materials and specifications are subject to change without notice.

	LS-BGA60C-61 Drawing © 2008 IRONWOOD ELECTRONICS, INC. 11351 Rupp Drive, Suite 400, Burnsville, MN 55337 Tele: (952) 229-8200 www.ironwoodelectronics.com	Status: Released	Scale: 6:1	Rev: C
		Drawing: M.A. Fedde		Date: 2/25/08
		File: LS-BGA60C-61 Dwg.mcd		Modified: 01/17/13, DH